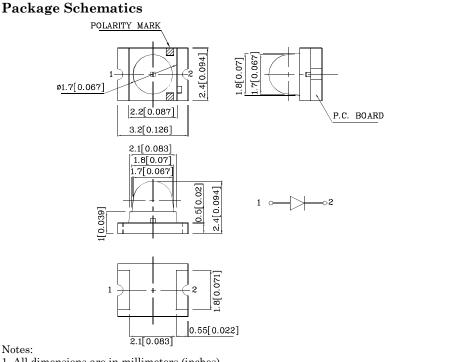


Part Number: XZMDK147W

3.2x2.4mm SMD CHIP LED LAMP

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package : 1500pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant





1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to change without notice.

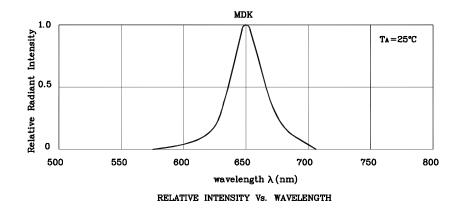
Absolute Maximum Ratings (T _A =25°C)	MDK (AlGaInP)	Unit			
Reverse Voltage	V_{R}	5	V		
Forward Current	\mathbf{I}_{F}	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA		
Power Dissipation	PD	75	mW		
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C		
Storage Temperature	Tstg	-40 ~ +85	C		

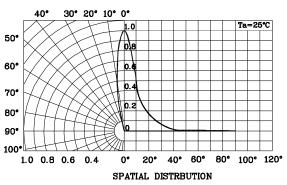
Operating Characteristics (T _A =25°C)		MDK (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.95	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	650	nm	
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	630	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	28	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	$_{\rm pF}$	

min. typ.		Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
						min.	typ.		
XZMDK147W Red AlGainP Water Clear 1300 2690 650 20	X	ZMDK147W	Red	AlGaInP	Water Clear	1300	2690	650	20°

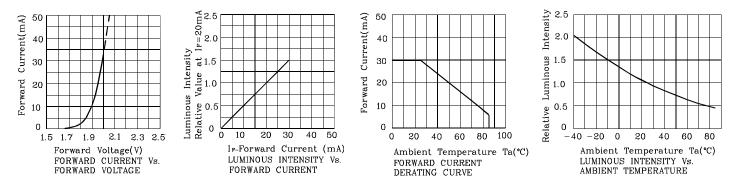
XDSB6186 V1 Layout: Maggie L.







✤ MDK



LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes: 1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C

3. Do not put stress to the epoxy resin during

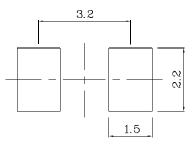
high temperatures conditions

XDSB6186 V1 Layout: Maggie L.

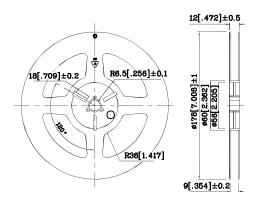


✤ The device has a single mounting surface. The device must be mounted according to the specifications.

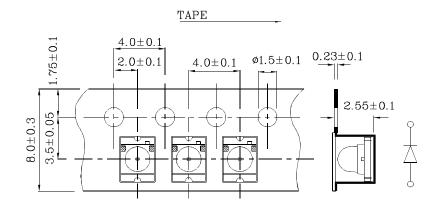
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15\%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

Jul 01,2011



PACKING & LABEL SPECIFICATIONS

